



**COCONUT INDUSTRY INVESTMENT FUND - San Pablo Manufacturing
Corporation Disposal Committee**

Bid Bulletin No.: 1 8 October 2025

Project Name : “DISPOSAL OF VARIOUS UNSERVICEABLE PROPERTIES AND WASTE MATERIALS LOCATED AT SAN PABLO MANUFACTURING CORPORATION CAIP-SEZ, SAN PASCUAL, BATANGAS ON BY LOT AND AS IS WHERE IS BASIS”

Project Number : ITB No. 2025-09-SPMC-001

This Supplemental/Bid Bulletin is issued to all prospective bidders to clarify, modify and/or amend pertinent items in the Philippine Bidding Documents for the above-mentioned project of Coconut Industry Investment Fund – San Pablo Manufacturing Corporation (SPMC).

The following clarifications and/or amendments are provided for the guidance and reference of all prospective bidders:

I. CLARIFICATIONS/SUPPLEMENTAL

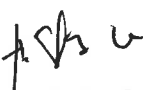
QUERY	CLARIFICATION/SUPPLEMENTAL
Section III – Terms and Conditions and Instructions to Bidders xxx Preparation of Bids 10.2 Each bidder shall submit one (1) original and two (2) copies of the components of its bid. In case of discrepancy among the copies, the original shall govern. a. How many envelopes inside technical and financial component? b. Where does the bid bond belong? c. How many copies of bid bonds to produce?	Section VI – Terms and Conditions and Instructions to Bidders xxx xxx a. There will be a one mother envelope for technical components. Inside the mother envelope are three envelopes wherein one (1) encloses original copies and the other two (2) encloses the copies/photocopies and one (1) envelope for the bid bond. The same applies to financial where there should mother envelope and three envelopes in it for wherein one (1) encloses original copies and the other two (2) encloses the copies/photocopies. The mother envelopes should be labeled properly as technical component and financial component.

d. Should we put the bid bond in the mother envelope of the technical component? Xxx (Ref. Page 21)	b. Bid bond belongs to the technical component. c. Acceptable bid bond is composed of cash or manager's check or combination thereof. Therefore, there are no copies for them, only one original. d. Bid bond should be placed in a separate envelope and be put inside the technical component mother envelope. Xxx (Ref. Page 21)
Xxx a. Is there a need to provide a USB for electronic copy of the bidding documents submitted? Xxx	Xxx a. No. No need to submit USB. Xxx

All other portions of the Bidding Documents affected by these amendments shall be made to conform to the same.

Amendments/inclusions/clarifications made herein shall be made integral part of the Bidding Documents.

For information and guidance of all concerned.


Horacio R. Tagle
Disposal Committee Chairperson